

描述 / Descriptions

SOT-323 塑封封装 PNP 半导体三极管。Silicon PNP transistor in a SOT-323 Plastic Package.

特征 / Features

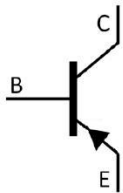
与 MMBTA06W 互补。

Complements the MMBTA06W.

用途 / Applications

用于一般放大电路。

General purpose amplifier.

内部等效电路 / Equivalent Circuit**引脚排列 / Pinning**

PIN1 : Emitter

PIN 2 : Base

PIN 3 : Collector

印章代码 / Marking

h_{FE} Range	>100
Marking	HR2G

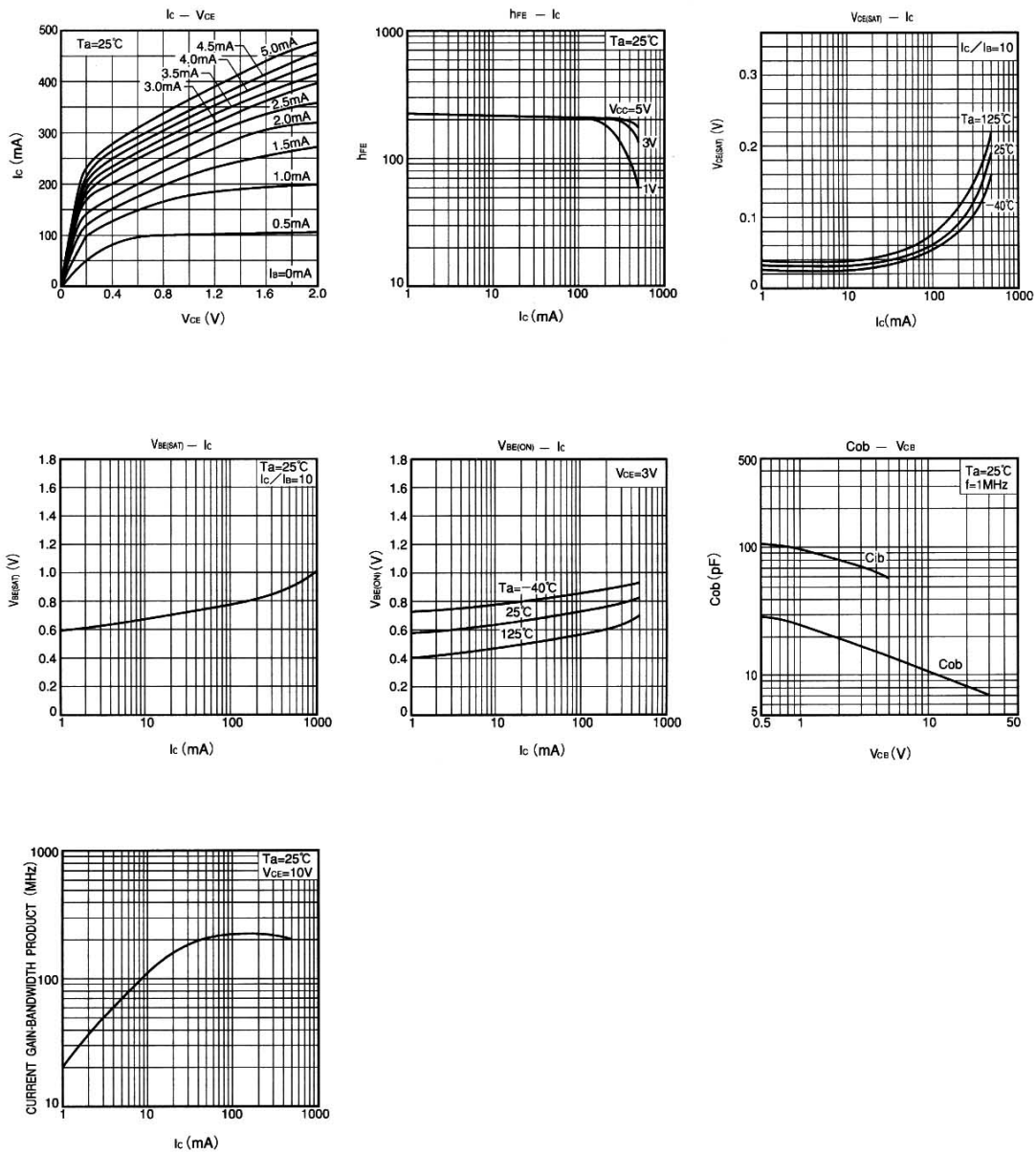
极限参数 / Absolute Maximum Ratings(Ta=25°C)

参数 Parameter	符号 Symbol	数值 Rating	单位 Unit
Collector to Base Voltage	V_{CBO}	-80	V
Collector to Emitter Voltage	V_{CEO}	-80	V
Emitter to Base Voltage	V_{EBO}	-5.0	V
Collector Current - Continuous	I_C	-0.5	A
Collector Power Dissipation	P_C	150	mW
Junction Temperature	T_j	150	°C
Storage Temperature Range	T_{stg}	-55~150	°C

电性能参数 / Electrical Characteristics(Ta=25°C)

参数 Parameter	符号 Symbol	测试条件 Test Conditions	最小值 Min	典型值 Typ	最大值 Max	单位 Unit
Collector to Base Breakdown Voltage	V_{CBO}	$I_C = -100\mu A$ $I_E = 0$	-80			V
Collector to Emitter Breakdown Voltage	V_{CEO}	$I_C = -1.0mA$ $I_B = 0$	-80			V
Collector Cut-Off Current	I_{CBO}	$V_{CB} = -80V$ $I_E = 0$			-0.1	μA
Emitter Cut-Off Current	I_{CEO}	$V_{CB} = -60V$ $I_B = 0$			-1.0	μA
Emitter Base Cut-Off Current	I_{EBO}	$V_{BE} = -4.0V$ $I_C = 0$			-0.1	μA
DC Current Gain	$h_{FE(1)}$	$V_{CE} = -1.0V$ $I_C = -100mA$	100			
	$h_{FE(2)}$	$V_{CE} = -1.0V$ $I_C = -10mA$	100			
Collector to Emitter Saturation Voltage	$V_{CE(sat)}$	$I_C = -100mA$ $I_B = -10mA$			-0.25	V
Base-Emitter On Voltage	V_{BE}	$V_{CE} = -1.0V$ $I_B = -100mA$			-1.2	V
Transition Frequency	f_T	$I_E = 100mA$ $f = 100MHz$ $V_{CE} = -1.0V$	50			MHz

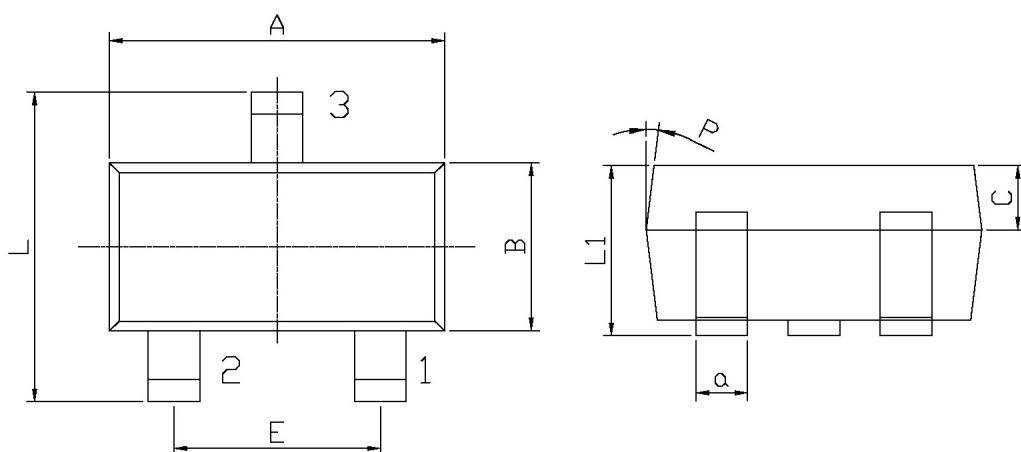
电参数曲线图 / Electrical Characteristic Curve



外形尺寸图 / Package Dimensions

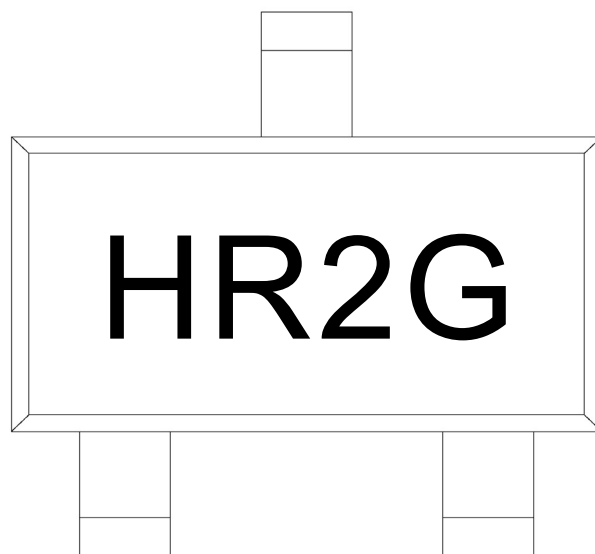
SOT-323

单位: mm



Symbol	Dimensions In Millimeters		Symbol	Dimensions In Millimeters	
	Min	Max		Min	Max
A	1.95	2.35	C	0.30	0.50
L	2.00	2.2	L1	0.85	1.15
E	1.20	1.40	a	0.20	0.40
B	1.15	1.35	P	7°	

印章说明 / Marking Instructions



说明：

H： 为公司代码

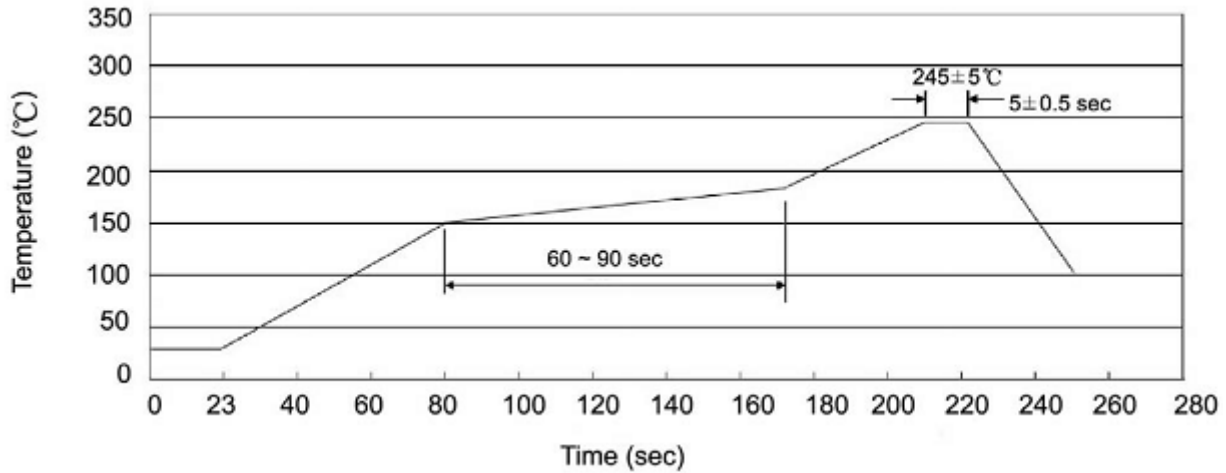
R2G： 为型号代码

Note:

H: Company Code.

R2G: Product Type Code

回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：

- 1、预热温度 25 ~ 150°C，时间 60 ~ 90sec;
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2 ~ 10°C/sec.

Note:

- 1.Preheating:25~150°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：260±5°C

时间：10±1 sec.

Temp.:260±5°C

Time:10±1 sec

包装规格 / Packaging SPEC.

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOT-323	3,000	10	30,000	8	240,000	7" x8	180×120×180	385×257×392

使用说明 / Notices